CXA1875AP/AM

8-bit D/A Converter Compatible with I²C Bus

Description

The CXA1875AP/AM is developed as a 8-bit 5 ch D/A converter compatible with I²C bus.

Features

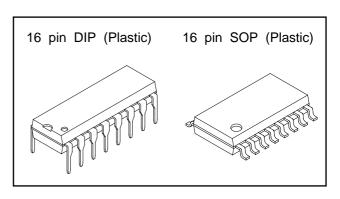
- Serial control through I2C bus
- 4 built-in general purpose I/O ports (Digital I/O)
- I/O can be specified to respective ports independently
- Selection of 8 slave addresses possible through address select pins (3 pins)

Applications

I²C bus can control ICs that do not correspond to I²C bus by connecting the DC control pins of them.

Structure

Bipolar silicon monolithic IC



Absolute Maximum Ratings (Ta=25°C)

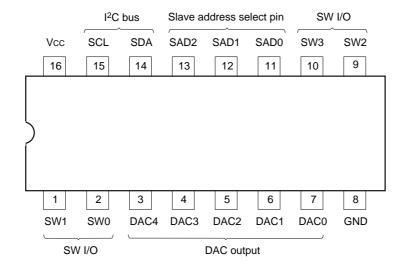
	- '	•	
 Supply voltage 	Vcc	7	V
• Operating temperature	Topr	-20 to +75	°C
Storage temperature	Tstg	-65 to +150	°C
• Allowable power dissipa	ation		
	PD	960	mW

Operating Conditions

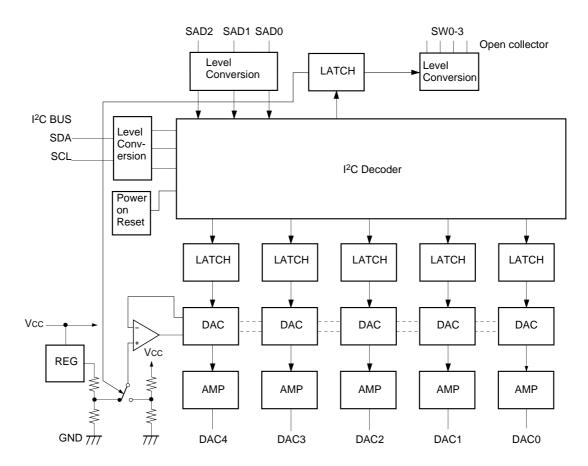
 Supply voltage 	Vcc	5±0.5	V
 Operating temperature 	Topr	-20 to +75	°C

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Pin Configuration (Top View)



Block Diagram



Pin Description

No.	Symbol	Equivalent circuit	Description
1	SW1	Vcc	I/O pin for general purpose I/O port
2	SW0		VILmax: 1.5 V
9	SW2		VIHmin: 3 V
10	SW3	150	Volmax: 0.4 V
14 15	SDA SCL	4.5k\$	SDA I/O pin for I ² C bus
3 4 5 6 7	DAC4 DAC3 DAC2 DAC1 DAC0	Vcc Vcc 56 22k W 7/77	D/A converter output pin
8	GND		GND pin
11 12 13	SAD0 SAD1 SAD2	Vcc ↓ 150 ↓ 4.5k €	Slave address input pin Input at positive logic VILmax: 1.5 V VIHmin: 3 V
16	Vcc	<i>III III</i>	Power supply pin

Electrical Characteristics (Ta=25°C, Vcc=5 V)

N	0.	Item	Symbol	Test circuit	Test contents	Min.	Тур.	Max.	Unit
	1	Circuit current	Icc	1	DAC 0 to 4=127	6	9	12	mA

D/A Converter Block

2	Differential linearity	DLE	1	V(DAC0 to 4=n+1)–V(DAC0 to 4=N) V(DAC0 to 4=191)–V(DAC0 to 4=63) ×128–1 n=0 to 127	– 1	0	+1	LSB
3	Minimum output voltage	Vmin	1	DAC 0 to 4=0	0.1	0.4	0.7	V
4	Maximum output voltage	Vmax	1	DAC 0 to 4=255	4.3	4.6	4.9	٧
5	Output current	lout	2	Current that can be flowed from Pins 3 to 7	-1		+1	mA
6	Output impedance	Zo	2	DAC 0 to 4=127, $\frac{V(-1mA)-V(1mA)}{2mA}$	0	3	6	Ω

SW, SAD Pins

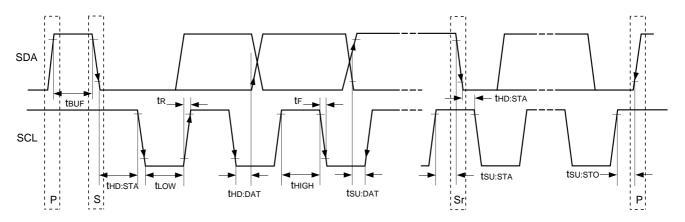
No.	Item	Symbol	Text circuit	Test contents	Min.	Тур.	Max.	Unit
7	Low level input voltage	VIL	3	ST 0 to 3 an input voltage that turns to '0'		_	1.5	V
8	High level input voltage	ViH	3	ST 0 to 3 an input voltage that turns to '1'		_	_	V
9	Low level input current	lıL	3	Input current when 0.4 V is applied	-10	0	+10	μA
10	High level input current	Іін	3	Input current when 4.5 V is applied		0	+10	μA
11	Low level input voltage	Vol	4	SW 0 to 3=1, Output voltage when 1mA flows in	0	0.2	0.4	V

I²C Bus Block Items (SDA, SCL)

No.	Item	Symbol	Min.	Тур.	Max.	Unit
12	High level input voltage	VIH	3.0	_	5.0	V
13	Low level input voltage	VIL	0	_	1.5	V
14	High level input current	IIH	_	_	10	μA
15	Low level input current	IIL	_	_	10	μA
16	Low level output voltage	VoL	0		0.4	V
10	At 3 mA flow to SDA (Pin 14)	VOL	0	_	0.4	V
17	Maximum flowing current	IOL	3	_	_	mΑ
18	Input capacitance	Сі	_	_	10	pF
19	Maximum clock frequency	fscl	0	_	100	kHz
20	Data change minimum waiting time	tBUF	4.7	_	_	μs
21	Data transfer start minimum waiting time	thd:STA	4.0	_	_	μs
22	Low level clock pulse width	tLOW	4.7	_	_	μs
23	High level clock pulse width	thigh	4.0	_	_	μs
24	Minimum start preparation waiting time	tsu:sta	4.7	_	_	μs
25	Minimum data hold time	thd:dat	5	_	_	μs
26	Minimum data preparation time	tsu:dat	250	_		ns
27	Rise time	tR		_	1	μs
28	Fall time	tF	_	_	300	ns
29	Minimum stop preparation waiting time	tsu:sto	4.7	_	_	μs

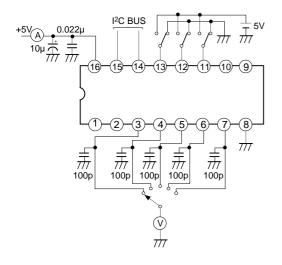
 $\mbox{I}^2\mbox{C}$ bus load conditions: Pull up resistance 4 k Ω (Connected to +5 V) Load capacitance 200 pF (Connected to GND)

I²C Bus Control Signal

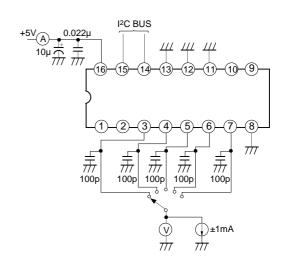


Electrical Characteristics Test Circuit

Test circuit 1

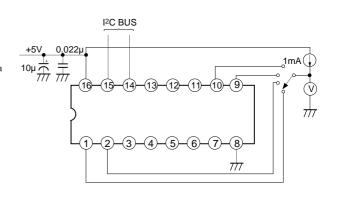


Test circuit 2



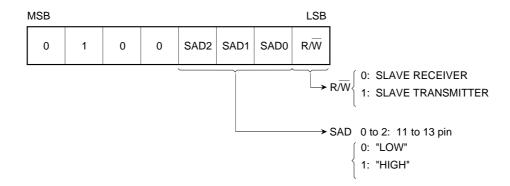
Test circuit 3

Test circuit 4



Definition of I²C Register

<Slave address>



<Register table>

- With the IC reset all registers are reset to 0
- *: Not defined
- x: Don't care
- Sub address is auto incremented
- It can be used as a 6-bit D/A converter by setting the lower two bits of DAC 0-4 registors to 0, but take care that the max. voltage of DA output will lower about 100 mV compared with the use of 8 bits.

Control Register

Sub address	BIT7	BIT6	BIT5	BIT4	BIT3	BIT2	BIT1	BIT0
×××× 000	REF	*	*	*	SW3	SW2	SW1	SW0
××××× 001				DAC	0 (8)			
××××× 010				DAC	1 (8)			
××××× 011				DAC	2 (8)			
××××× 100	DAC3 (8)							
××××× 101	DAC4 (8)							

Status Register

BIT7	BIT6	BIT5	BIT4	ВІТ3	BIT2	BIT1	ВІТ0
PONRES	0	0	0	ST3	ST2	ST1	ST0

<Registers> In brackets () number of bits

REF (1): Switches D/A converter reference voltage

0:Standardizes the inner regulator

1:Standardizes voltage resistance divided from Vcc

SW0 to 3 (1): Selects ON/OFF of Pins 1, 2, 9 and 10

(Each pin is the open collector output of NPN transistor)

0:OFF

1:ON

DAC0 to 4 (8): Digital data input register of D/A converter

0:Output voltage turns to minimum 255:Output voltage turns to maximum

PONRES (1): Detects POWER ON RESET

0:Master passes from the bus and is reset to 0 after having read this status1:Set to 1 when power supply is turned on or when there has been a power dip

ST0 to 3 (1): Detects and registers the voltage condition of Pins 1, 2, 9 and 10

0:1.5 V and below

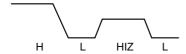
1:3.0 V and above

Note) SW0 to 3 effective during 0

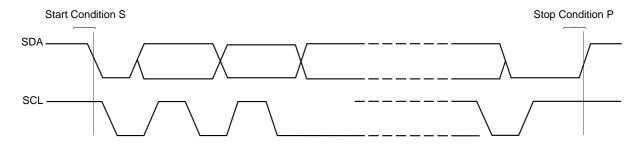
I²C Bus Signal

There are 2 signals in I²C bus. SDA (Serial DAta) and SCL (Serial Clock). SDA is double-way.

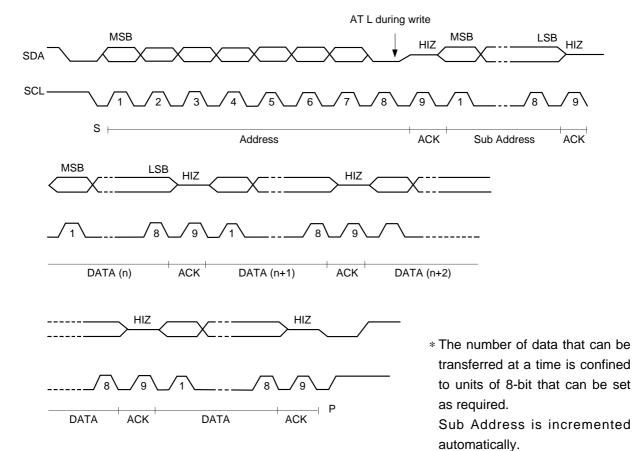
• As SDA is double-way it has 3 state outputs, H, L and HIZ.



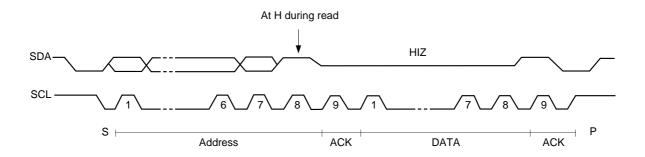
• I²C transfer begins with Start Condition and ends with Stop Condition.



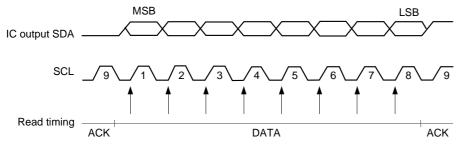
• I²C data write (Write from I²C controller to IC)



• I²C data read (Read from IC to I²C controller)

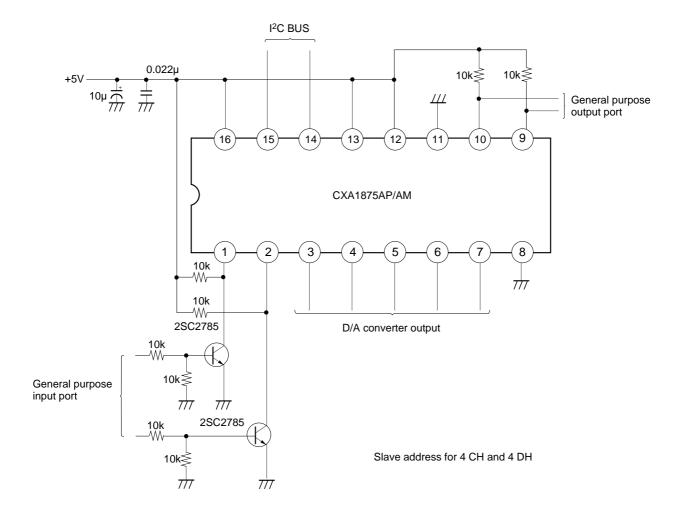


• Read timing



* Data read is performed with SCL rise.

Application Circuit

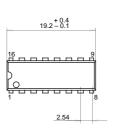


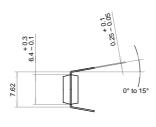
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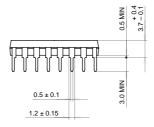
Package Outline Unit: mm

CXA1875AP

16PIN DIP (PLASTIC) 300mil







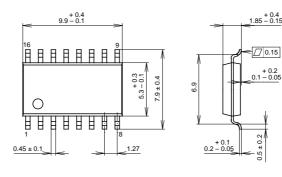
SONY CODE	DIP-16P-01
EIAJ CODE	*DIP016-P-0300-A
JEDEC CODE	Similar to MO-001-AE

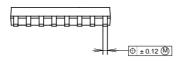
PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER
PACKAGE WEIGHT	1.0 g

CXA1875AM

16PIN SOP (PLASTIC) 300mil





SONY CODE	SOP-16P-L01
EIAJ CODE	*SOP016-P-0300-A
JEDEC CODE	

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	COPPER ALLOY
PACKAGE WEIGHT	0.2g

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